Ordering number: EN2076D



The LC6520C/H are single-chip 4-bit microcomputers that contain a 4K-byte ROM, 1K-bit RAM, have 42 pins, and are fabricated using CMOS process technology. Besides 8 input/output common ports of 32 pins and an input port of 4 pins, the LC6520C/H have specific ports that are used to provide the interrupt function, 4-bit/8-bit serial input/output function, and burst pulse output function. All output ports are of the open drain type with a withstand voltage of 15 V and a drive current of 20 mA and have the option of containing a pull-up resistance bitwise.

The LC6520C/H are the same as our LC6500 series in the basic architecture of the CPU and the instruction set, but are made more powerful in the stack level and the cycle time.

The LC6522C/H are the same as the LC6520C/H, except that they contain a 2k-byte ROM, 512-bit RAM.

Features

- Instruction set with 80 instructions (Common to the LC6500 series)
- ROM/RAM
 - : 4096 bytes/1024 bits (LC6520C/H)
 - 2048 bytes/512 bits (LC6522C/H)
- Instruction cycle time: $6 \mu s$ (C version, $V_{DD} = 3 \text{ to } 5.5 \text{V}$)
 - 2.77 μs (C version, V_{DD} = 4 to 5.5V)
 - 9.92 μ s (H version, VDD = 4.5 to 5.5V)
- Serial input/output interface x 1 (4 bits/8 bits program-selectable)

I/O ports

Input port: 4 pins

Input/output common ports: 32 pins

Input · input/output withstand voltage: 15 V max (all input · input/output ports)

- Output current: 20 mA max (all output ports)
- Pull-up resistance: May be contained bitwise by option. (All output ports)

Output level during reset: For ports C, D, output (H or L) during reset may be specified portwise by option.

Package Dimensions 3025B-D42SIC (unit: mm)





Package Dimensions 3052A-Q48A1C



SANYO Electric Co., Ltd. Semiconductor Business Headquarters TOKYO OFFICE Tokyo Bldg., 1-10, 1 Chome, Ueno, Taito-ku, TOKYO, 110 JAPAN

5202HK / 4209TA / 7137KI / 4176KI,TS No.2076-1/29

- Interrupt function
 - Timer interrupt: 1
 - INT pin or serial I/O interrupt: 1
- Stack level: 8 levels (common with interrupt)
- Timer: 4-bit prescaler + 8-bit programmable timer
- Burst pulse (64 x cycle time, duty 50%) output function
- Oscillator option Circuit mode: Ceramic mode, RC mode, external clock mode (200 kHz to 4.2 MHz) (Xtal OSC constants are being checked.)
 - Predivider option: 1/1, 1/3, 1/4
- Standby function: Standby function provided by the HALT instruction
- Supply Voltage: 3 to 5.5 V (C version)
 - 4.5 to 5.5 V (H version)
- Package: DIP42 shrink type, QIP48



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Pin Description

Pin Name	Pins	¥/O	Functions	Options	During Reset	
V _{DD} Vss	1		Power supply			
OSC1	1	Input	 Pin for externally connecting R, C or a ceramic resonator for system clock superstion 	 External clock input 2-pin RC OSC 2-pin ceramic 		
OSC2	1	Output	Output For the external clock mode, the OSC2 pin is open. I. No. predivider I. 73 predivider I. 1/3 predivider 			
PA0 PA1 PA2 PA3	4	Input/output	 Input/output common port A0 to 3. 4-bit input (IP instruction) 4-bit output (OP instruction) Single-bit decision (BP, BNP instructions) Single-bit set/reset (SPB, RPB instructions) Standby is controlled by the PA3 (or PA0 to 3). The PA3 (or PA0 to 3) pin must be free from chattering during the HALT instruction cycle. 	 (1) Open drain type output (2) With pull-up resistance (1), (2): Specified bit by bit. 	• "H" output (Output Nch transistor OFF)	
РВО РВ1 РВ2 РВ3	4	Input	 Input Port B0 to 3 4-bit input (IP instruction) Single-bit decision (BP, BNP instructions) 			
PC0 PC1 PC2 PC3	4	Input/output	 Input/output common port Cg to 3. The functions are the same as for the PAg to 3. (Note) Output ("H" or "L") during reset may be specified by option. (Note) No standby control function is provided. 	 Open drain type output With pull-up resistance Output during reset: "H" Output during reset: "L" (1), (2): Specified bit by bit. (3), (4): Specified in a group of 4 bits. 	 "H" output "L" output (Option- selectable) 	
PD0 PD1 PD2 PD3	4	Input/output	 Input/output common port D₀ to 3 The functions, options are the same as for the PC₀ to 3. 	Same as for the PCO to 3.	Same as for the PC ₀ to 3.	
PEO PE1 PE2 PE3	4	Input/output	 Input/output common port EQ to 3 4-bit input (IP instruction) 4-bit output (OP instruction) Single-bit decision (BP, BNP instructions) 	 (1) Open drain type output (2) With pull-up resistance (1), (2): Specified bit by bit. 	• "H" output (Output Nch transistor OFF)	

	Cont	inued on next page.
Single-bit set/reset (SPB, RPB instructions) • PEO: With burst pulse (64T _{cyc}) output function		

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Continued from preceding page.

Pin Name	Pins	1/0	Functions	Options	During Reset
PF0/SI PF1/SO PF2/ <u>SCK</u> PF3/INT	4	Input/output	 Input/output port Fg to 3 The functions, options are the same as for the PEg to 3. However, no burst pulse output function is provided. PFg to 3: Also used for serial interface, INT input. Program- selectable. 4 bits/8 bits of serial input/output: Program-selectable SI: Serial input port SO: Serial output port SCK: Serial clock input/output INT: Interrupt request input 	Same as for the PE _O to 3.	Same as for the PE0 to 3. Serial port: Disable Interrupt source: INT
PGD PG1 PG2 PG3	4	Input/output	 Input/output common port G₀ to 3 The functions, options are the same as for the PE₀ to 3. However, no burst pulse output function is provided. 	Same as for the PEO to 3.	Same as for the PE0 to 3.
P10 P11 P12 P13	4	Input/output	 Input/output common port 10 to 3 The functions, options are the same as for the PG0 to 3. 	Same as for the PG0 to 3.	Same as for the PG0 to 3.
PJ0 PJ1 PJ2 PJ3	4	Input/output	 Input/output common port J0 to 3 The functions, options are the same as for the PG0 to 3. 	Same as for the PGO to 3.	Same as for the PG ₀ to 3.
RES	1	Input	 System reset input For power-up reset, C is connected externally. For reset start, "L" level is applied for 4 clock cycles or more. 		
TEST	1	Input	 LSI test pin Normally connected to VSS 		

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System Block Diagram



RAM:	Data memory	ROM:	Program memory
F:	Flag	PC:	Program counter
WR:	Working register	INT:	Interrupt control
AC:	Accumulator	1R:	Instruction register
ALU:	Arithmetic and logic unit	i.DEC:	Instruction decoder
DP:	Data pointer	CF, CSF:	Carry flag, carry save flag
E:	E register	ZF, ZSF:	Zero flag, zero save flag
CTL:	Control register	EXTF:	External interrupt request flag
OSC:	Oscillator	TMF:	Internal interrupt request flag
TM:	Timer		

STS: Status register

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Oscillator Circuit Option

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Option Name	Circuit	Conditions, etc.
1. External Clock	л о́сі ф	Input: Schmitt type
2. 2-pin RC OSC	Cext OSC1	 Input: Schmitt type
3. Ceramic Resonator OSC	C1 OSC1 Ceramic OSC 2 resonator OSC 2 C2 R	

• Predivider Option

Option Name	Circuit	Conditions, etc.
1. No predivider	OSC circuit Generator	 Applicable to all of 3 OSC options. The OSC frequency, external clock do not exceed 1444 kHz. (LC6520C, LC6522C) The OSC frequency, external clock do not exceed 4330 kHz. (LC6520H, LC6522H) Refer to Table of OSC, Predivider Option (Table 2).
2, 1/3 predivider	D	 Applicable to only 2 options of external clock, ceramic resonator OSC. The OSC frequency, external clock do not exceed 4330 kHz. Refer to Table of OSC, Predivider Option (Table-2).
3. 1/4 predivider		 Applicable to only 2 options of external clock, ceramic resonator OSC. The OSC frequency, external clock do not exceed 4330 kHz. Refer to table of OSC, Predivider Option (Table 2).

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Options of Ports C, D Output Level during Reset For input/output common ports C, D, either of the following two output levels may be selected in a group of 4 bits during reset by option.

Option Name	Conditions, etc.
1. Output during reset: "H" level	All of 4 bits of ports C, D
2. Output during reset: "L" level	All of 4 bits of ports C, D

Options of Port Output Configuration

For each input/output-common port, either of the following two output configurations may be selected by option (bitwise).

Option Name	Circuit	Conditions, etc.
1. Open drain type output		
2. Output with pull-up resistance		

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Development Support

The following are available to support the LC6520, LC6522 program development.

- (1) User's Manual
 - "LC6554 Series User's Manual" No. E21B. (Issued in December, 1987)
- (2) Development Tool Manual

For the EVA-410 system, refer to the description of Development Support Tools in "LC6554 Series User's Manual". For the EVA-800 system, refer to "EVA-800-LC6554 Series Development Tool Manual".

- (3) Development Tools
 - 1) For program development (EVA-410 system)
 - i. MS-DOS host computer system (Note 1)
 - ii. MS-DOS base cross assembler (LC65S.EXE)
 - iii. Evaluation kit (EVA-410C or EVA-420)
 - iv. Evaluation kit target board (EVA-TB6520/22/54/43/46), evaluation chip (LC6595)
 - 2) For program evaluation
 - i. Piggyback (LC65PG20/22), with socket for conversion of number of piggyback pins

Note. For notes on program evaluation, do not fail to refer to "5-3-1. Notes on when evaluating programs for the LC6520/22" in "LC6554 Series User's Manual".

Appearance of Application Development Tools

EVA-410 System

Piggyback





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- 3) For program development (EVA-800 system)
 - i. IBM PC/XT, IBM PC-AT (Note 1) compatible Sanyo MS-DOS machine
 - ii. Cross assemblerMS-DOS base cross assembler: (LC65S.EXE)
 - iii. Host control program: (EVA800.EXE)
 - iv. Evaluation chip: LC6595
 - v. Emulator : EVA-800 or EVA-850 control board and evaluation chip board (Note 2)

Appearance of Development Support System

EVA-800 System



(Note 1) IBM PC/XT, IBM PC-AT: Products of IBM Corporation MS-DOS: Trademark of Microsoft Corporation

(Note 2) The EVA-800 is a general term for emulator. A suffix (A, B ...) is added at the end of EVA-800 as the EVA-800 is improved to be a newer version. Do not use the EVA-800 with no suffix added.

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Main Specifications of the L	.C6520C, (6522C			
Absolute Maximum Batings/T _n :	= 25°C Vee	= OV		unit	
Maximum Supply Voltage		Vpp	-0.3 to $+7.0$	V	
Output Voltage	Vo	OSC2 Allowable up to volta	oe generated	v	
	Vi (1)	OSC1 (Note 1) -0.3	to $V \rightarrow 0.3$	v	
input voltage	$V_{1}(2)$	TEST $\overline{\text{RES}}$ -0.3	to $V_{DD}+0.3$	v	
	$V_1(3)$	PBo to 2	-0.3 to $+15$	v	
Input/Output Voltage	$V_{10}(1)$	Port of OD type	-0.3 to $+15$	v	
input output Follage	Vio (2)	Port of PLI type0.3	to Vpp+0.3	v	
Peak Output Current		Input/output port	-2 to +20	mΑ	
Average Output Current		Input/output port	-2 to $+20$	mΔ	
Average Output Current	DA	Per pip over the period of 100 msec	-2 10 120		
	ΣΙ _{ΟΑ} (1)	Total current of PAQ to 3, PCQ to 3,	30 to +140	mA	
	ΣΙ _{ΟΑ} (2)	Total current of PF0 to 3, PG0 to 3,	-30 to +140	mA	
		PIO to 3 and PJO to 3, (Note 2)			
Allowable Power Dissipation	Pd max (1)	DIP package, $T_a = -30$ to $+70^{\circ}C$	600	mW	
	Pd max (2)	QIP package, $T_a = -30$ to $+70^{\circ}C$	400	mW	
Operating Temperature	Торг		-30 to +70	°C	
Storage Temperature	т _{stg}		-55 to +125	°C	
Allowable Operating Conditions	/T _a =30 to	o +70°C, V _{SS} ≕ 0V, V _{DD} = 3.0 to 5.5\	/ min	typ max	unit
Operating Supply Voltage	VDD	VDD	3.0	5,5	V
Standby Supply Voltage	V _{st}	VDD: RAM, resister hold (Note 3)	1.8	5.5	V
"H"-Level Input Voltage	V _{IH} (1)	Port of OD type, PB0 to 3: Output Nch Tr OFF	0.7VDD	+13.5	V
	Viн (2)	Port of PU type: Output Nch Tr OFF	0.7Vpp	Vpp	V
	VIH (3)	SCK, SI, INT of OD type: Output Nch Tr OFF	0.8VDD	+13.5	V
	Viн (4)	SCK, SI, INT of PU type:	0.8Vnn	Vpp	V
		Output Nch Tr OFF	00	00	
	Viн (5)	RES	0.8V nn	Voo	V
	Viн (6)	OSC1: External clock mode	0.8Vnn	Voo	v
	• 111 • • •				
			min	typ max	unit
"L"-Level Input Voltage	V][(1)	PORT: VDD = 4 to 5.5V, Output Nch Tr OFF	VSS	0.3VDD	V
	V⊺L (2)	PORT: Output Nch Tr OFF	Vss	0.25V _{DD}	V
	V;L (3)	INT, SCK, SI: V _{DD} = 4 to 5.5V Output Nch Tr OFF	V _{SS}	0.25V _{DD}	V
	V1L (4)	INT, SCK, SI: Output Nch Tr OFF	Vss	0.2V _{DD}	V
	V1L (5)	OSC1: V _{DD} = 4 to 5.5V, External clock mode	VSS	0,25V _{DD}	V
	V11 (6)	OSC1: External clock mode	Vss	0.2V _{DD}	V
	V11. (7)	TEST: VDD = 4 to 5.5V	Vss	0.3Vnn	v
	VII (8)	TEST	Vss	0.25Vnn	v
	V11 (9)	RES: Von = 4 to 5.5V	Vee	0.25Vnn	v
	VII (10)	RES	Vee	0.2Vnn	v
Operating Frequency	fon		100	See Table 2.	-
(Cycle Time)	(Teve)	(VDD = 4.0 to 5.5V)	(2.77)	(20)	(µs)
, . , · · · · · · · · · · · · · · · ·	U UyU		(6.0)	(20)	(μs)

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External Clock Conditions (Whe	en the extern	al clock or 2-pin RC OSC option is sele	ected) mir	ı typ	max	unit
Frequency	fext	OSC1: Fig. 1		See Tabl	e 2.	
Pulse Width	(textH,	OSC1: $V_{DD} = 4$ to 5.5V, Fig. 1	90			ns
	LtextL	OSC1: Fig. 1	180			nŝ
Rise/Fall Time	textR,	OSC1: $V_{DD} = 4$ to 5.5V, Fig. 1			30	ns
	textF	OSC1: Fig. 1			100	ns
Oscillation Guaranteed Cons	tants			220+59/		- E
2-Pin RC Oscillation	Cext	OSC1, OSC2; VDD = 4 to 5.5V, Fig. 2	2	220±5%		pr LO
	Rext	OSC1, OSC2: VDD = 4 to 5.5V, Fig. 2	2	0,0±1%		K32
	Cext	OSC1, OSC2: Fig. 2		27015%		μ LO
	Rext	OSC1, USC2: Fig. 2		D±1%	- 1	K75
Ceramic Resonator Oscillatio	on	Fig. 3		See 1901	ΕΙ.	
Electrical Characteristics/Ta = -	-30 to +70°($C_{1} V_{SS} = 0V_{1} V_{DD} = 3.0 \text{ to } 5.5 \text{V}$	min	typ	max	unit
"H"-Level Input Current	<u>ын (1)</u>	Port of open drain type, PBo to 3:			+5.0	μA
		Output Nch Tr OFF, Including OFF				
		leakage current of Nch Tr.				
		$V_{1N} = +13.5V$				
	IH (2)	OSC1: External clock mode, VIN = V	סס		+1.0	μA
"L"-Level Input Current	10 (1)	Port of open drain type, PBn to 3:	-1.0)		μA
· · · · · · · · · · · · · · · · · · ·		Output Nch Tr OFF, VIN = VSS				•
	b) (2)	Port with pull-up resistance:	-1.3	-0.35		mΑ
		Output Nch Tr OFF, VIN = Vss				
	lii (3)	RES: VIN = VSS	-45	-10		μA
	lii (4)	OSC1: External clock mode,	-1.0	-		μA
		$V_{IN} = V_{SS}$				
"H"-Level Output Voltage	Vон (1)	Port with pull-up resistance:	Vpp-1.2	1		V
	011.11	$V_{DD} = 4 \text{ to } 5.5 \text{V}$. $I_{OH} = -50 \mu\text{A}$	00			
	Vон (2)	Port with pull-up resistance:	0.5–מת V	i		V
	011	$I_{OH} = -10 \mu A$	00			
"L"-Level Output Voltage	VOL (1)	Port: VDD = 4 to 5.5V, IOL = 10 mA			1.5	V
	VOL (2)	Port: IOL = 1 mA, When IOL of			0.5	V
		each port is 1 mA or less.				
Hysteresis Voltage	v_{Hvs}	RES, INT, SCK, SI,		0.1V _{DD}		V
		OSC1 of Schmitt type (Note 6)				
Current Dissipation		Operation mode, Output Neb Tr OFF	Port - V	D .0		
2 Pin BC Oscillation	10000 (1)	Vpp: Vpp = 4 to 5 5V. Eig. 2	, Pont - V	200	5	mΔ
	'DDOP (II	$f_{a,a} = 750 \text{ kHz typ}$		2	5	
	$l_{\rm DDOD}(2)$	V_{DD} : Eig. 2 from = 350 kHz typ		15	45	mΔ
Ceramic Resonator		V_{DD} ; Fig. 3 $V_{DD} = 4$ to 5 5V 4MHz		5	10	mΔ
Oscillation	10000000	1/3 predivider	,	0	10	1174
		Vop: Fig. 3 Vop = 4 to 5.5V $4MHz$		5	10	mΑ
	·DDOP (4)	1/4 predivider	,	Ū	10	
		Vpp: Fig. 3 400kHz		1.5	4	mΑ
	(6) and	Vpp: Vpp = 4 to 5.5V. Fig. 3 800k	Hz	2	5	mA
External Clock	1000P (7)	Vnn: 200 kHz to 667 kHz.		2	5	mΑ
	0001	1/1 predivider			-	
		600 kHz to 2000 kHz, 1/3 predivider				
		800 kHz to 2667 kHz, 1/4 predivider				
	IDDOP (8)	V_{DD} : $V_{DD} = 4$ to 5.5V.		3	10	mΑ
		200 kHz to 1444 kHz, 1/1 predivider				
		600 kHz to 4330 kHz, 1/3 predivider				
		800 kHz to 4330 kHz, 1/4 predivider				
Standby Mode	1DDSt	VDD: VDD = 5.5V (Output Nch Tr C	DFF,	0.05	10	μA
		V_{DD} : $V_{DD} = 3V$ UPort = V_{DD}		0.025	5	μA

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Continued from preceding page. Oscillation Characteristics			min	typ	max	unit
Ceramic Resonator Oscillatio	ń					
Oscillation Frequency	fcfosc	OSC1, OSC2: Fig. 3 f ₀ = 400 kHz	392	400	408	kHz
	(Note 4)	OSC1, OSC2: $V_{DD} = 4$ to 5.5V,	784	800	816	kHz
		Fig. 3 f _o = 800 kHz				
		OSC1, OSC2: $V_{DD} = 4$ to 5.5V,	2940	3000	3060	kHz
		Fig. 3 f _o = 3 MHz, 1/3 predivider,				
		1/4 predivider				
		OSC1, OSC2: $V_{DD} = 4$ to 5.5V,	3920	4000	4080	kHz
		Fig. 3 f _o = 4 MHz, 1/3 predivider,				
		1/4 predivider			_	
Oscillation Stabilizing	tCFS	Fig. 4 f ₀ = 400 kHz			10	ms
Period		V _{DD} = 4 to 5.5V, Fig. 4			10	ms
		f _o = 4 MHz, 3 MHz, 800 kHz				
2-Pin RC Oscillation						
Oscillation Frequency	fMOSC (1)	OSC1, OSC2: $V_{DD} = 4$ to 5.5V, Fig. 2,	515	750	1156	kHz
		$C_{ext} = 220 \text{ pF}\pm 5\%, R_{ext} = 6.8 \text{ k}\Omega\pm 1\%$				
	fMOSC (2)	OSC1, OSC2: Fig. 2,	222	350	609	кНz
		$C_{ext} = 270 \text{ pF} \pm 5\%, R_{ext} = 15 \text{ k}\Omega \pm 1\%$				
Pull-up Resistance		· ••				
I/O Port Pull-up Resistance	Rpp	Port of PU type: V_D = 5V		14		kΩ
External Reset Characteristics	PP					
"H"-Level Threshold	VtH		0.5V _{DD}	0	.8VDD	v
"L"-Level Threshold	VtL		0.2V _{DD}	0	.5VDD	v
Reset Time	TRST			See Fig	g. 5.	
Pin Capacitance	CP	f = 1 MHz, Other than pins to be		10		pΕ
		tested, VIN = VSS				
Serial Clock						
Input Clock Cycle Time	tCKCY (1)	<u>SCK</u> : V _{DD} = 4 to 5.5V, Fig. 6	3.0			μs
		SCK	12.0			μs
Output Clock Cycle Time	^t CKCY (2)	SCK (T _{CYC} = 4 x System clock	64	х тсүс		μs
_		<u>perio</u> d), Fig. 6				
Input Clock	tCKL (1)	<u>SCK</u> : V_{DD} = 4 to 5.5V, Fig. 6	1.0			μs
L''L''-Level Pulse Width		SCK	4.0			μs
Output Clock	tCKL (2)	SCK, Fig. 6	32	х тсус		μs
L"L"-Level Pulse Width						
Input Clock	<u>t</u> СКН (1)	SCK: VDD = 4 to 5.5V, Fig. 6	1.0			μs
C"H"-Level Pulse Width		SCK	4.0	-		μs
Output Clock	tCKH (2)	SCK: Fig. 6	32	× ¹ CYC		μs
C"H"-Level Pulse Width						
Serial Input						
Data Setup Time	TICK	SI: Specified for T of SCK, Fig. 6	0.5			μs
Data Hold Time	ĨCKI	SI: Specified for 1 of SUK, Fig. 6	0.5			μs
Serial Output					0.5	
Output Delay Time	чско	SU: $v_{DD} = 4$ to 5.5 v,			0.5	μs
		Neb OD only External 1 kebm				
		Non OD only: External 1 Konni,				
		external 50 pF, Fig. 0			20	
Pulse Output		30			2.0	μι
Period	toov	PEO: Toyo = $4x$ System clock period	64	x Toyo		116
i criod	40.1	Nch OD only: External 1 kohm	, 01	~ .010		μ .5
		external 50 pF. Fig. 7				
"H"-Level Pulse Width	teu	PEO:	32 x 1	CVC±1	0%	us
"L"-Level Pulse Width	tei	PEO:	32 x 1		D%	μs
				510.1		

Note 1: When oscillated internally under the oscillating conditions in Fig. 3, up to the oscillation amplitude generated is altowable.

Note 2: Average over the period of 100 msec.

Note 3: Operating supply voltage VDD must be held until the standby mode is entered after the execution of the

- HALT instruction,
 The PA3 (or PA0 to 3) pin must be free from chattering during the HALT instruction execution cycle.
 Note 4: fCFOSC represents an oscillatable frequency. There is a tolerance of approximately 1% between the center frequency at the ceramic mode and the nominal value presented by the ceramic resonator supplier. For details, refer to the specification for the ceramic resonator. Note 5: When mounting the QIP version on the board, do not dip it in solder. Note 6: The OSC1 becomes the Schmitt type when the OSC option is the 2-pin RC OSC or external clock OSC.

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Fig. 2 2-Pin RC Oscillation Circuit







Fig. 3 Ceramic Resonator Oscillation Circuit



Note 7: When the rise time of the power supply is 0, the reset time becomes 10 ms to 100 ms at CRES = 0.1 μ F. If the rise time of the power supply is long, the value of CRES must be increased so that the reset time becomes

10 ms or greater.

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4MHz (Murata)	C1	33pf ± 10%
CSA4.00MG	٢2	33pf±10%
	R	OΩ
4MHz (Kyocera)	C1	33pf ± 10%
KBR4,0MS	¢2	33pf ± 10%
	R	<u>η</u> Ω
3MHz (Murata)	C 1	$33 p_F \pm 10\%$
CSA3.00MG	C2	33pf±10%
	R	0 \2
3MHz (Kyocera)	٢1	47pf±10%
KBR3.0MS	C2	47pf±10%
	R	0Ω

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800kHz (Murata)	C 1	220pf±10%
CSB800D CSB800K	¢2	220pf±10%
CSBBUUK	Ŕ	QΩ
800kHz (Kyocera)	c 1	150pf±10%
KBR800H	٢2	150pf±10%
	R	ΟΩ
400kHz (Murata)	c 1	470pf±10%
CSB400P	c2	470pf±10%
	R	OΩ
400kHz (Kyocera)	c 1	330pf±10%
KBR400B	c2	330pf±10%
	R	0Ω

Table 1 Constants Guaranteed for Ceramic Resonator Oscillation



Fig. 6 Serial Input/Output Timing



Fig. 7 Pulse Output Timing at Port PE0

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Circuit Configuration	Frequency	Predivider Option (Cycle Time)	V _{DD}	Remarks
Ceramic Resonator Option	400 kHz	1/1 (10 μs)	3 to 5.5V	Unusable with 1/3, 1/4 predivider
	800 kHz	1/1 (5 μs) 1/3 (15 μs) 1/4 (20 μs)	4 to 5.5V 4 to 5.5V 4 to 5.5V	
	3 MHz	1/3 (4 μs) 1/4 (5.33 μs)	4 to 5.5∨ 4 to 5.5∨	Unusable with 1/1 predivider
	4 MHz	1/3 (3 μs) 1/4 (4 μs)	4 to 5.5V 4 to 5.5V	Unusable with 1/1 predivider
External Clock Option or External Clock Drive by RC OSC Option	200 to 667 kHz 600 to 2000 kHz 800 to 2667 kHz 200 to 1444 kHz 600 to 4330 kHz 800 to 4330 kHz	1/1 (20 to 6 μs) 1/3 (20 to 6 μs) 1/4 (20 to 6 μs) 1/1 (20 to 2.77 μs) 1/3 (20 to 2.77 μs) 1/4 (20 to 3.70 μs)	3 to 5.5V 3 to 5.5V 3 to 5.5V 4 to 5.5V 4 to 5.5V 4 to 5.5V	
External Clock Drive by ceramic resonator OSC Option	The external clock specify the externa	drive is impossible. When I clock option or RC OSC	using the external option.	al clock drive,
RC OSC Option	Used with 1/1 pred VDD = 3 to 5.5V). If used with other t frequency, VDD ra	ivider, recommended con than recommended const nge must be the same as f	istants (V _{DD} = 4 ants, the predivid for the external c	to 5.5V, er option, lock option.

 Table 2 Table of Oscillation, Predivider Option (All selectable combinations are shown. Do not use any other combinations than shown above.)

RC Oscillation Characteristic of the LC6520C, 6522C

Fig. 8 shows the RC oscillation characteristic of the LC6520C, 6522C. For the variation range of RC OSC frequency of the LC6520C, 6522C, the following are guaranteed at the external constants only shown below.

1) $V_{DD} = 3.0V$ to 5.5V, $T_a = -30^{\circ}C$ to $+70^{\circ}C$ External constants 2) $V_{DD} = 4.0V$ to 5.5V, $T_a = -30^{\circ}C$ to $+70^{\circ}C$ External constants External constants External constants External constants $515 \text{ kHz} \le f_{mosc} \le 1156 \text{ kHz}$

If any other constants than specified above are used, the range of Rext = 4 kohms to 23 kohms, Cext = 150 pF to 400 pF must be observed. (See Fig. 8.)

Note 8: The oscillation frequency at $V_{DD} = 5.0V$, $T_a = 25^{\circ}C$ must be in the range of 350 kHz to 750 kHz. Note 9: The oscillation frequency at $V_{DD} = 4.0V$ to 5.5V, $T_a = -30^{\circ}C$ to $+70^{\circ}C$ and $V_{DD} = 3.0V$ to 5.5V, $T_a = -30^{\circ}C$ to $+70^{\circ}C$ must be within the operation clock frequency range. (See Table 2.)

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LC6520C,6520H,6522C,6522H

		•0	Allowable up to to:	tage generated	•	
	Input Voltage	Vj (1)	OSC1 (Note 1) -0.	3 to VDD+0.3	V	
		Vi (2)	TEST, RES -0.	3 to VDD+0.3	V	
		Vi (3)	PB0 to 3	-0.3 to +15	V	
	Input/Output Voltage	Vio (1)	Port of OD type	–0.3 to +15	V	
		Vio (2)	Port of PU type -0.	3 to VDD+0.3	v	
	Peak Output Current	IOP	Input/output port	-2 to +20	mA	
	Average Output Current	IOA	Input/output port: Per pin over	-2 to +20	mA	
			the period of 100 msec.			
		ΣΙΟΑ (1)	Total current of PAO to 3, PCO to 3,	30 to +140	mA	
			PD0 to 3, and PE0 to 3 (Note 2)			
		ΣΙΟΑ (2)	Total current of PF0 to 3, PG0 to 3,	-30 to +140	mA	
			and Plo to 3, PJo to 3 (Note 2)			
	Allowable Power Dissipation	Pd max (1)	DIP package, $T_a = -30 \text{ to } +70^{\circ}\text{C}$	600	mW	
		Pd max (2)	QIP package, $T_a = -30 \text{ to } +70^{\circ}\text{C}$	400	mW	
	Operating Frequency	Topg		— 30 to +70	°C	
	Storage Temperature	Tstg		–55 to +125	°C	
Α	lowable Operating Conditions	/T _a =30 to	$h + 70^{\circ}C, V_{SS} = 0V, V_{DD} = 4.5 \text{ to } 5.5$	iV min	typ max	unit
	Operating Supply Voltage	VDD	VDD	4,5	5.5	V
	Standby Supply Voltage	Vst	VDD: RAM, resister hold (Note 3)	1.8	5.5	V
	"H"-Level Input Voltage	VIH (1)	Port of OD type, PB0 to 3:	0.7V _{DD}	+13.5	V
			Output Nch Tr OFF			
		VIH (2)	Port of PU type: Output Nch Tr OFF	• 0.7V _{DD}	VDD	V
		VIH (3)	SCK, SI, INT: Output Nch Tr OFF	0.8VDD	+13.5	V
		VIH (4)	SCK, SI, INT: Output Nch Tr OFF	0.8VDD	VDD	V
		VIH (5)	RES	0.8VDD	VDD	V
		V1H (6)	OSC1: External clock mode	0.8VDD	VDD	V
	"L"-Level Input Voltage	VIL (1)	Port: Output Nch Tr OFF	VSS	0.3∨ _{DD}	V
		V _{IL} (2)	INT, SCK, SI: Output Nch Tr OFF	VSS	0.25V _{DD}	V
		VIL (3)	OSC1: External clock mode	VSS	0.25V _{DD}	V
		VIL (4)	TEST	VSS	0.3VDD	V
				N /		11
		VIL (5)	HES	vss	0.25VDD	v
	Operating Frequency	fop	RES	VSS See Ta	0.25VDD able 2.	v

External Clock Conditions (When the external clock option is selected) Frequency fext OSC1: Fig. 1

See Table 2.

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		<u>, , , , , , , , , , , , , , , , , , , </u>	No	2076-16/29
Oscillation Guaranteed Constants Ceramic Resonator Oscillation		Fig. 2	See Table 1,	۱
Rise/Fall Time	(^t extL (^t extR, t _{ext} F	OSC1: Fig. 1	30) ns
Pulse Width	(textH)	OSC1: Fig. 1	90	ns
	· EA L			

A DESCRIPTION OF THE OWNER OWNE

Electrical Characteristics/ $T_a = -$	30 to +70°C	C, V _{SS} = 0V, V _{DD} = 4.5 to 5.5V	min	typ	max	unit
"H"-Level Input Current	կը (1)	Port of open drain type,			+5.0	μA
		PBO to 3: Output Nch Tr OFF,				
		Including Nch Tr OFF leakage curre	nt,			
		VIN = 13.5V				
	Чн (2)	OSC1: External clock mode, VIN =	VDD		+1.0	μA
"L"-Level Input Current	կը (1)	Port of open drain type, PB0 to 3:	1.0			μA
		Output Nch Tr OFF, VIN = VSS				
	կլ (2)	Port with pull-up resistance:	-1,3	-0.35		mΑ
		Output Nch Ir OFF, VIN = VSS	45			
	11L (3)	RES: $V_{IN} = V_{SS}$	-45	-10		μΑ
	IIL (4)	USC1: External clock mode,	-1,0			μΑ
	M = (1)		V== 10			
"H"-Level Output Voltage	vон (т)	Port with pull-up resistance:	VDD-1.2			v
	Var. (2)	$IOH = -50 \mu A$				v
	VOH (2)	For with pull-up resistance.	VDD=0.5			v
"I "J evel Output Voltage	V_{OL} (1)	Port: lou = 10 mA			15	v
		Port: $I_{OI} = 1 \text{ mA}$ When I_{OI} of eac	Ь		0.5	v
	VUL (2/	port is 1 mA or less.			0.0	•
Hysteresis Voltage	VHvs	RES. INT. SCK. SI.	0	.1Vnn		v
	-1193	OSC1 of Schmitt type (Note 6)	-			
Current Dissipation						
Ceramic Resonator	DDOP (1)	VDD: Fig. 2, 4MHz, Operating mode	э,	5	10	mΑ
Oscillation		Output Nch Tr OFF, Port = VDD				
External Clock	DDOP (2)	V _{DD} : 200 kHz to 4330 kHz,		5	10	mΑ
		Operating mode, Output Nch Tr OF	F,			
		Port = VDD				
Standby Mode	DDST	V _{DD} : V _{DD} = 5.5V Output Nch Tr	OFF,	0.05	10	μA
		V _{DD} : V _{DD} = 3V (Port = V _{DD}		0.025	5	μA
Oscillation Characteristics						
Ceramic Resonator Oscillatio	n					
Oscillation Frequency	fores	OSC1 $OSC2$; Eig 2 fr = 4 MHz	3920	4000	4080	kHz
esemation (requeries	(Note 4)	0001,0002.1 lg.2 lg 4 line	0020	1000	1000	
Oscillation Stabilizing	toes	Fig. 3 fo ≕ 4 MHz			10	ms
Period	-013					
Pull-up Resistance						
I/O Port Pull-up Resistance	8 _{nn}	Port of PU type: Von = 5V		14		kΩ
External Reset Characteristics	PP					
"H"-Level Threshold	VtH		0.5V _{DD}	0	.8Vpp	V
"L"-Level Threshold	VtL		0.25VDD	0	,5V _{DD}	V
Reset Time	TRST		Se	e Fig. 4.		
Pin Capacitance	CP	f = 1 MHz, Other than pins to be		10		pF
		tested, VIN = VSS				
Serial Clock						
Input Clock Cycle Time	tCKCY (1)	SCK: Fig. 5	3.0			μs
Output Clock Cycle Time	tCKCY (2)	SCK: $(T_{CYC} = 4 \times System clock)$	64	× TCYC		μs
		period), Fig. 5				
Input Clock "L"-Level	tCKL (1)	SUK: Fig. 5	1,0			μs
Pulse Width	A	COV. Eta E		v Terre		
Pulse Width	CKL (2)	JUN: FIL. D	32	^ CYC		μs

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Continued from preceding page	min	typ	max	unit		
Input Clock ''H''-Level Pulse Width	tскн (1)	SCK: Fig. 5	1.0			μs
Output Clock "H"-Level Pulse Width	tCKH (2)	SCK: Fig. 5	32 ×	TCYC		μs
Serial Input						
Data Setup Time	ϤCK	SI: Specified for 1 of SCK, Fig. 5	0.5			μs
Data Hold Time	^t CKI	SI: Specified for 1 of SCK, Fig. 5	0.5			μs
Serial Output						
Output Delay Time	ţCKO	SO: Specified for ↓ of SCK, Nch OD only: External 1 kohm, external 50 pF, Fig. 5			0.5	μs
Pulse Output						
Period	tPCY	PE0: T _{CYC} = 4 × System clock period, Nch OD only: External 1 kohm, external 50 pF, Fig. 6	64 ×	TCYC		μs
"H"-Level Pulse Width	tрн	PEO:	3:	2 × Toyo	±10%	μs
"L"-Level Pulse Width	tPL	PEO:	3:	2 × TCYC		μs

- Note 1: When oscillated internally under the oscillating conditions in Fig. 2, up to the oscillation amplitude generated is allowable.
- Note 2: Average over the period of 100 msec.
- Note 3: Operating supply voltage V_{DD} must be held until the standby mode is entered after the execution of the HALT instruction. The PA3 (or PA0 to 3) pin must be free from chattering during the HALT instruction execution cycle.
- Note 4: fCFOSC represents an oscillatable frequency. There is a tolerance of approximately 1% between the center frequency at the ceramic mode and the nominal value presented by the ceramic resonator supplier. For details, refer to the specification for the ceramic resonator.
- Note 5: When mounting the QIP version on the board, do not dip it in solder.
- Note 6: The OSC1 becomes the Schmitt type when the OSC option is the external clock OSC.







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4MHz (Murata)	c 1	33pf±10%
CSA4.00MG	C 2	33pf±10%
	R	0Ω
4MHz (Kyocera) KBR4.0MS	c 1	33pf ± 10%
	C 2	33pf±10%
	R	QΩ

Table 1 Constants Guaranteed for Ceramic Resonator Oscillation



Fig. 4 Reset Circuit

Note 7: When the rise time of the power supply is 0, the reset time becomes 10 ms to 100 ms at $C_{RES} = 0.1 \ \mu F$. If the rise time of the power supply is long, the value of C_{RES} must be increased so that the reset time becomes 10 ms or greater.







Fig. 5 Serial Input/Output Timing



The load conditions are the same as in Fig. 5.



Circuit Configuration	Frequency	Predivider Option (Cycle Time)	V _{DD}	Remarks
Ceramic Resonator OSC Option	4 MHz	1/1 (1 μs)	4.5 to 5.5V	
External Clock Option	200 to 4330 kHz	1/1 (20 to 0.92 µs)	4.5 to 5.5V	
External Clock Drive	The external clock	drive is impossible. When	using the external	clock drive,

by Ceramic Resonator OSC Option specify the external clock option.

Table 2 Table of Oscillation, Predivider Option (All selectable combinations are shown. Do not use any other combinations than shown above.)

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Notes for Standby Function Application

The LC6520, LC6522 provide the standby function called HALT mode to minimize the current dissipation when the program is in the wait state.

The standby function is controlled by the HALT instruction, PA pin, RES pin, and serial transfer completion signal. A peripheral circuit and program must be so designed as to provide precise control of the standby function. In most applications where the standby function is performed, voltage regulation, instantaneous break of power, and external noise are not negligible. When designing an application circuit and program, whether or not to take some measures must be considered according to the extent to which these factors are allowed. This section mainly describes power failure backup for which the standby function is mostly used. A sample application circuit where the standby function is performed precisely is shown below and notes for circuit design and program design are also given below.

When using the standby function, the application circuit shown below must be used and the notes must be also fully observed.

If any other method than shown in this section is applied, it is necessary to fully check the environmental conditions such as power failure and the actual operation of an application equipment.

1. HALT mode release conditions

1-1, Supplementary description of release by serial transfer completion signal

On completion of serial transfer, the HALT mode is released and the execution of the program starts with an instruction immediately following the HALT instruction. This function can be used to execute the program only when serial transfer occurs, placing the program in the wait state when no serial transfer occurs. This function is effective in reducing the current dissipation or clock noise.

- Notes -

- Release by the serial transfer completion signal is available only when the RC mode is used for system clock generation; and unavailable when the ceramic mode is used.
- On completion of serial transfer, the HALT mode is released unconditionally. In an application, such as capacitor backup application, where the current dissipation must be kept as low as possible during backup and serial transfer by external clock is also used, the HALT mode is released when serial data is transferred externally during backup.

1-2, Summary of HALT release conditions

The HALT mode setting, release conditions are shown in Table 1.

Table 1 HALT mode setting, release conditions

HALT mode setting conditions	HALT mode release conditions
HALT instruction Provided that PA3, (PA3 to PA0 or PA3 is program- selectable) is at high level.	 Reset (Low level is appled to RES.) Low level is applied to PA3, (PA3 to PA0 or PA3 is program-selectable.) Serial transfer completion.

Note) HALT mode release conditions (2), (3) are available only when the RC mode is used for system clock generation; and unavailable when the ceramic mode is used.

2. Proper cares in using standby function

When using the standby function, an application circuit and program must be designed with the following in mind. (1) The supply voltage at the standby state must not be less than specified.

- (2) Input timing and conditions of each control signal (RES, port A, serial transfer) must be observed at the standby initiate/release state.
- (3) Release operation must not be overlapped at the time of execution of the HALT instruction.

A sample application where the standby function is used for power failure backup is shown below as a concrete

method to observe these notes. A sample application circuit, its operation, and notes for program design are given below.

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Sample application where the standby function is used for power failure backup

Power failure backup is an application where power failure of the main power source is detected and the HALT instruction is executed to cause the standby state to be entered. The current dissipation is minimized and a backup capacitor is used to retain the contents of the internal registers for a certain period of time. After power is restored, a reset occurs automatically and the execution of the program starts at address 000H of the program counter (PC). Shown below are sample applications where the program selects or not between power-ON reset and reset after power is restored, notes, measures for instantaneous break of AC power, and notes for serial transfer.

2-7. Sample application 1 where the standby function is used for power failure backup Shown below is a sample application where the program does not select between power-ON reset and reset after power is restored.

2-1-1. Sample application circuit - (1)

Fig. 2-1 shows a sample application where the standby function is used for power failure backup.



Fig. 2-1. Sample application - (1) where the standby function is used for power failure backup

2-1-2. Operating waveform in sample application circuit -- (1)

The operating waveform in the sample application circuit in Fig. 2-1 is shown in Fig. 2-2. The mode is roughly divided as follows: a, Power-ON reset, b, Instantaneous break of main power, C, Return from power failure backup.



HALT instruction

(c) Return from power failure backup

V+TRON: V+ value when TR is turned ON/OFF

Fig. 2-2. Operating waveforms - (1) in sample application circuit

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2-1-3. Operation of sample application circuit - (1)

(a) At the time of power-ON reset

After power rises, a reset occurs automatically and the execution of the program starts at address 000H of the program counter (PC).

- Note -

This sample application circuit provides an indeterminate region where no reset occurs before the operating V_{DD} range is entered.

- (b) At the time of instantaneous break
 - (i) When the PXX input voltage does not meet VIL (The PXX input level does not get lower than input threshold level VIL) and the RES input voltage only meets VIL:
 - A reset occurs in the normal mode, providing the same operation as power-ON reset.
 - (ii) When both of the PXX input voltage and RES input voltage do not meet VIL: The program continues running in the normal mode.
 - (iii) When both of the PXX input voltage and RES input voltage meet VIL: When two pollings do not regard the PXX input voltage as "L" level, the HALT mode is not entered and a reset occurs.

When two pollings regard the P_{XX} input voltage as "L" level, the HALT mode is entered and after power is restored a reset occurs, releasing the standby mode.

(c) At the time of return from power failure backup After power is restored, a reset occurs, releasing the standby mode.

2-1-4. Notes for design of sample application circuit - (1)

V+rise time and C2

Make the time constant (C₂, R) of the reset circuit 10 times as long as the V+rise time. (R: ON-chip resistor, 500 kohm typ.)

- Make the V+rise time shorter (up to 20 ms).
- R1 and C1

Make the R_1 value as small as possible. Make the C_1 value as large as possible according to the backup time calculated, (Fix the R_1 value so that the C_1 charging current does not exceed the power source capacity.)

R₂ and R₃

Make the "H"-level input voltage applied to the PXX pin equal to VDD.

• R4

Fix the time constant of C₂ and C₄ so that C₂ can discharge during the period of time from when V+ gets lower than V+TROM (TR OFF) at the time of instantaneous break until the P_{XX} input voltage gets lower than V_{IL} (because release by reset is not available after the HALT mode is entered by instantaneous break).

R5 and R6

Make V+ (V_{BE} \Rightarrow 0.6V is obtained by R5 and R6) when the reset circuit works (Tr ON) more than (operating V_{DD} min + V_F of diode D1). Observing this note, make V+ as low as possible to provide a reset early enough after power-ON.

Backup time

The normal operation continues with a relatively high current dissipation from when power failure is detected by the P_{XX} until the HALT instruction is executed. Fix the C₁ value so that the standby supply voltage is held during backup time of set + above-mentioned time.

2-1-5. Notes for software design

- Design the program so that port A0 to A2 cannot be used for standby release and port A3 is brought to "H" level at the standby mode.
- Input a standby request to a normal input port other than the PA3 and check by polling this input port twice.

(Example)

BP1	AAA	; 1st polling
RCTL	3	; Interrupt inhibit
BP1	AAA	; 2nd polling
ΗΔΙΤ		: Standby

AAA: :

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- 2.2. Sample application 2 where the standby function is used for power failure backup Shown below is a sample application where the program selects between power-ON reset and reset after power is restored.
- D1 Unit (resistance: Ω) v+ 100V AC R1 power source (50)≩ TR 2 VDD Pxx (Note) (SENSE) ٧٥ C1 R2 (~1F) ₹(Ю**0**к) R3 🗲 777 (100k) ¥₽₽ ≩ R (500k) D2 R4 (10k) (TYP) RES <u>⊅</u> ⊂2 R5 (82×) (≯µF) Vss , TR R6 (12k) (Note) Normal input ports other than PA3
- 2-2-1. Sample application circuit (2) (No instantaneous break in power source) Fig. 2-3 shows a sample application where the standby function is used for power failure backup.



- 2-2-2. Operating waveform in sample application circuit (2)
 - The operating waveform in the sample application circuit in Fig. 2-3 is shown in Fig. 2-4. The mode is roughtly divided as follows: a, Power-ON reset, b. Return from power failure backup.



FXX-

V+TRON: V+ value when TR1 is turned ON/OFF.

Fig. 2-4. Operating waveform - (2) in sample application circuit

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2-2-3. Operation of sample application circuit - (2)

- (a) At the time of power-ON reset
 - The operation and notes are the same as for sample application circuit (1), except that after reset release $P_{XX} = "L"$ is program-detected to decide program start after initial reset.
- (b) Standby initiation
- When one polling regards the P_{XX} input voltage as "L" level, the HALT mode is entered. (c) At the time of return from power failure backup
- After power is restored, a reset occurs, releasing the standby mode. After standby release $P_{XX} = ''H''$ is program-detected, deciding program start after power is restored.
- -- Note --

If power is restored after V_{DD} during power failure backup gets lower than V_{IH} on the P_{XX} , $P_{XX} = "L"$ may be program-detected, deciding program start after initial reset.

2-2-4. Notes for design of sample application circuit -(2)

- R₂ and R₃
- Fix the R_2 value so that $R_2 \gg R_1$ is yielded and fix the R_3 value so that Ig of TR2 is limited. • R_4

There is no severe restriction on the R4 value, but fix it so that C2 can discharge quickly. Other notes are the same as for sample application circuit - (1).

2-2-5. Notes for software design

- Design the program so that port A0 to A2 cannot be used for standby release and port A3 is brought to "H" level.
- Input a standby request to a normal input port other than the PA3 and check by polling this input port once.

(Example)			
	: BP1 HALT	AAA	;	Polling Standby
AAA:	:		•	,

2-3. Sample application 3 where the standby function is used for power failure backup

2-3-1. Sample application circuit -- (3) (There is an instantaneous break in power source.)
 Fig. 2-5, shows a sample application where the standby function is used for power failure backup.





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2-3-2. Operating waveform in sample application circuit - (3)

The operating waveform in the sample application circuit in fig. 2-5 is shown in Fig. 2-6. The mode is roughly divided as follows: a, Power-ON reset, b, Instantaneous break of main power, C, Return from power failure backup.



Fig. 2-6. Operating waveform in sample application circuit – (3)

2-3-3. Operation of sample application circuit - (3)

(a) At the time of power-ON reset

- The operation and notes are the same as for sample application circuit (2)
- (b) At the time of instantaneous break
 - (i) When the PXX input voltage does not meet VIL (the PXX input level does not get lower than input threshold level VIL) and the RES input voltage only meets VIL:
 - A reset occurs in the normal mode. After reset release $P_{XX} = "H"$ is program-detected, deciding program start after instantaneous break.
 - (ii) When both of the P_{XX} input voltage and \overline{RES} input voltage do not meet VIL:
 - The program continues running in the normal mode.
 - (iii) When both of the PXX input voltage and RES input voltage meet V11:
 When two pollings do not regard the PXX input voltage as "L" level, the HALT mode is not entered and a reset occurs.
 When two pollings regard the PXX input voltage as "L" level, the HALT mode is entered and after

power is restored, a reset occurs, releasing the standby mode. After standby release $P_{XX} = "H"$ is program-detected, deciding program start after instantaneous break.

(c) At the time of return from power failure backup
 The operation and notes are the same as for sample application circuit -- (2)

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2-3-4. Notes for design of sample application circuit - (3)

• R3

- Bias resistance of TR2
- R7 and R8

Fix the R7 and R8 values so that TR3 is turned ON/OFF at approximately 1.5V of V+. Other notes are the same as for sample application circuit -(1)

2-3-5. Notes for software design

Same as for sample application circuit -(1)

2-4. Notes (1) for providing serial transfer

Notes for providing power failure backup and serial transfer

This application assigns top priority to power failure backup. When power failure backup is provided, serial transfer may not be provided normally.

- (1) When the internal clock is used for the serial clock:
 - Execute the serial transfer start instruction immediately before executing the HALT instruction. If this is done during serial transfer, the power failure backup mode is entered without normal transfer.
- (2) When the external clock is used for the serial clock:

When power failure is detected, it is most prioritized that the HALT mode is entered, providing power failure backup. It is necessary to design an application system where no release signal by serial transfer completion is inputted to the HALT instruction executing cycle and no release signal is inputted during backup.

2-5. Notes (2) for providing serial transfer

Notes for providing HALT and serial transfer for program standby without power failure backup

This application assigns top priority to serial transfer. The following notes for system design must be observed.(1) When the internal clock is used for the serial clock:

Transfer starts when it is ready on both sides. When transfer is not ready on the other side, the HALT instruction is executed to reduce the current dissipation. When transfer is ready, the HALT release signal (RES, PA) causes return from the standby mode, starting serial transfer.

(2) When the external clock is used for the serial clock:

Synchronization must be provided between microcomputers to prevent the HALT instruction and HALT release signal (RSIOEND) from overlapping. When transfer is ready, the serial transfer start instruction is executed and the program is placed in the wait state. The other side adjusts thime so that no overlap occurs between the HALT instruction and transfer completion and starts serial transfer. On completion of transfer, the HALT mode is released and the program is executed with an instruction immediately following the HALT instruction.

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LC6520, LC6522 INSTRUCTION SET

	Symbol AC AC CF CTL DP E EXTF Fn M	Description : Accumulator : Accumulator bit t : Carry flag : Control register : Data pointer : E register : E register : External interrupt request : Fleg bit n : Memory	t flag	M(DP) : P(DPL) : PC : STACK : TM : TMF : At, Ha, La : ZF :	Merri Inpu Prog Stac Time Time Vorl Zero	hory it/ou iram k re er er (in king i flag	addressed by DP toput port addressed by DP counter gister nternall interrupt request fla register }	(), [] : Contents ← : Transfer and direction + : Addition - : Subtraction A : AND SG V : OR ∀ : Exclusive OR		
Instruction		Mnemonic	1nstruc 07060504	tion code D ₃ D ₂ D ₁ D ₀	Bytes	Cycles	Function	Description	Status flag affected	Remarks
2	CLA	Clear AC	1100	0000	1;	1	AC + 0	The AC contents are cleared.	ZF	* 1
latio	CLC	Clear CF	1 1 1 0	0001	1	1	CF ←0	The CF contents are cleared.	CF	
UBU	STC	Se1 CF	1 1 1 1	0001	11	1	CF ←1	The CF is set.	CF	
ion	CMA	Complement AC	1110	1011	11	ı		The AC contents are complemented.	ZF	
pulat	INC	Increment AC	0000	1 1 1 0	1	1	AC -(AC) + 1	The AC contents are incremented +1.	ZF CF	
nanig	DEC	Décrement AC	0000	1 1 1 1	1	1	AC - (AC) - 1	The AC contents are decremented -1.	ZF CF	
ulator n	RAL	Rotate AC left through CF	όοοο	0001	,	1	$AC_0 \leftarrow (CF), AC_{n+1} \leftarrow (AC_n), CF \leftarrow (AC_3)$	The AC contents are shifted left through the CF.	ZF CF	
E D X	TAE	Transfer AC to E	0 0 0 0	0011	1	1	E ← (AC)	The AC contents are transferred to the E.		
¥	XAE	Exchange AC with E	0000	1 1 0 1	1	1	(AC) ≒(E)	The AC contents and the E conents are exchanged.		
	INM	Increment M	0010	1 1 1 0	1	1	M(DP) + (M(DP))+1	The M(DP) contents are incremented +1.	ZF CF	
	DE M	Decrement M	0010	1 1 1 1	1	۱	$M(DP) \leftarrow (M(DP)) + 1$	The M(DP) contents are decremented -1.	ZF CF	
	SMB bit	Set M data bit	0000	1 O B 18 c	1	ı	M(DP, B₁B₀) ⊷1	A single bit of the $M(DP)$ specified with B_1B_0 is set.		
instruc	RMB bit	Resel M data bit	0010	1 0 B 1 B c	1	1	M(DP. B ₁ B ₀) ←0	A single bit of the $M(DP)$ specified with B_1B_0 is reset.	ZF	
	AD	Add M to AC	0110	0 0 0 0	1	1	AC +-(AC) + (M(DP))	Binary addition of the AC contents and the M(DP) contents is performed and the result is stored in the AC.	ZF CF	
	ADC	Add M to AC with CF	0010	0 0 0 0	,	1	AC ←(AC) + [M(DP)] +(CF)	and the M(DP) contents is performed and the result is stored in the AC.	ZF CF	
	DAA	Decimal adjust AC in addition	1 1 1 0	0110	ŀ	,	AC +1 AC) + 6	6 is added to the AC contents.	ZF	
	DAS	Decimal adjust AC in subtraction	1110	1010	1	۱ 	AC ←(AC)+10	10 is added to the AC contents.	2 F	
lotions	EXL	Exclusive or M to AC	1 1 1 1	0 1 0 1	1	1	AC ↔(AC) ¥ [M(DP)]	are exclusive-ORed and the result is stored in the AC. The AC contents and the M(DP) contents	ZF	
า เกริก	AND	And M to AC	1 1 1 0	0111	'	1	AC ←(AC) ∧ [M(DP)]	are ANDed and the result is stored in the AC.	2F	,
parisc	OR	Or M to AC	1110	0101	1	1	$AC \leftarrow (AC) \lor (M(DP))$	are ORed and the result is stored in the AC.	ZF	
hmetic operation/com	см	Compare AC with M	1 1 1 1	1011	1	1	(M(DP))+(AC)+1	The AC contents and the M(DP) contents are compared and the CF and ZF are set/reset. Comparison result CF ZF $(M(DP)) > (AC)$ 0 0 $(M(DP)) = (AC)$ 1 1 $(M(DP)) < (AC)$ 1 0	ZF CF	
Arit	CI data	Compare AC with immediate data	00100	1 1 0 0 3 2 1 0	2	2	₃ ₂ ₁ ₀ + (AC) + 1	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	ZF CF	
	CLI data	Compare DPL with Immediate data	0010100101	1 1 0 0 1 3 1 2 1 1 0	2	2	{DP ₁ } ¥ ₃ ₂ ₁ ₀	The DP contents and the immediate data $1_31_21_11_0$ are compared.	ZF	
	LI data	Load AC with immediate data	1 1 0 0	13121110	1	1	AC -13121110	The immediate data 13121110 is loaded in the AC.	ZF	* 1
	s	Store AC to M	0 0 0 0	0010	1	١	M(DP) ←(AC)	The AC contents are stored in the M(DP).		
	L	Load AC Irom M	0010	0 0 0 1	1	1	AC - (M(DP))	The M(DP) contents are loaded in the AC.	ZF	
stions	XM data	Exchange AC with M. then modily DPB with immediate data	1010	0 M2M1M		2	(AC) ≒ (M(DP)) DP _H ←(DP _H) ¥ 0 M 2 M 1 M 2	The AC contents and the M(DP) contents are exchanged and then the DP _H contents are modified with the contents of $(DP_H) \neq OM_{AM} \cdot M_{A}$.	ZF	The ZF is set/relation according to the result of (DP _H) vOM ₂ M ₁ Mo.
re instruc	×	Exchange AC with M	1010	0000	1	2	(AC) ≒ (M(DP))	The AC contents and the M{DP} contents are exchanged.	ZF	The ZF is set/reset according to the OP _H contents at the time of instruc

1 2		with minediate data		1	1 -1		Contains of the Hr Com 2m 1mg.		1
Load/store instru	x	Exchange AC with M	1010	0000	1 2	(AC) ≒ (M(DP))	The AC contents and the M{DP} contents are exchanged.	ZF	The ZF is set/reset according to the OP _M contents at the time of instruc- tion execution,
	X)	Exchange AC with M. then increment DP_L	1 1 1 1	1 1 1 0	1 2	(AC) ≒ (M(DP)) DPL ←(DPL) + 1	The AC contents and the M(DP) contents are exchanged and then the DPL contents are incremented +1.	ZF	The ZF is set/reset according to the result of IDPL +1)
	хo	Exchange AC with M, then decrement DPL	1 1 1 1	1111	1 2	(AC) \$\$ (M(DP)) DP1 ←(DP1) = 1	The AC contents and the M(DP) contents are exchanged and then the DPL contents are decremented -1.	ZF	The ZF is set/reset according to the result of tOP _L = 11
	RT BL	Read table data from program ROM	0110	0011	1 2	AC.E←ROM (PCh.E.AC)	The contents of ROM addressed by the PC whose low-order 8 bits are replaced with the E and AC contents are loaded in the AC and E.		

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Instruction code Status flag Remarks Mnemonic Instruc Function Description $D_7 D_6 D_5 U_4 | D_3 D_2 D_1 D_0 | \overset{\frown}{\delta} | \overset{\circ}{\delta}$ affected The DP_H and DP_L are loaded with 0 and the immediate data $1_31_21_10$ respectively. DPн ←0 DP1 ←13121110 LDZ data Load DPH with Zero and , E 000 13 12 11 10 DPL with immediate data respectively Į The DP_H is loaded with the immediate LHI data Load DPH with 0 1 0 0 13121110 1 1 DP∺ ← 13121110 data 13121110. immediate data Dulat Increment DPL IND 1110 1 1 1 0 1 1 DPL ← (DPL) + 1 The DPL contents are incremented +1. ZF Part of the DED 1110 1111 DPL - (OPL) - 1 The DPL contents are decremented -1. ZF Decrement DPL TAL The AC contents are transferred to the DPL Transfer AC to DPL 1 1 1 1 0 1 1 1 1 1 DP (~ (AC) pointe TLA The DPL contents are transferred to the AC ZF 1.1 1 0 1 0 0 1 1 1 AC ← (DPL) Transfer DPL to AC The AC contents and the DPH contents an 0 0 1 0 0 0 1 1 1 1 (ACI \$ (DPH) хан Exchange AC with DPH exchanged. The AC contents and the contents of working register At are exchanged. At is assigned one of A_0 , A_1 , A_2 , A_3 execution to tab. 11 10 XAt Exchange AC with working register At XAO (AC) \$ (AO) (AC) = (A1)(AC) = (A2)XAI according to t₁t₀. XA2 XA3 1 1 1 0 1 1 0 0 (AC) ≒(A3) The DP_L contents and the contents of working register Ha are exchanged, Ha is assigned either of H0 or H1 XHa 1 0 0 Exchange DPH with XH0 working register Ha 1 1 1 1 (DPH) \$(HO) хн1 1 1 1 1 1 1 0 0 (DPH) ≒(H1) according to a. The DPL contents and the contents of working register La are exchanged. La is assigned either of LO or L1 according Exchange DPc with XLə Wort Instri (DP1)=(L0) XLO working register. La 1 1 1 1 XLI 1 1 1 1 0 1 0 0 1 1 (DPL) =(L1) to e. SFB flag Set flag bit The flag specified with B3B2B1B0 is set. O I O I B3B2B1B0 I I Fn ← I The flags are divided into 4 groups of F₀ to F₀, F₄ to F₁, F₁ to F₁₅. F₁₀ to F₁₅. The ZF is set/reset according to the 4 bits including a single bits section and with the immediate dere $B_3B_2B_1B_0$. RFB flag Reset flag bit 0 0 0 1 83B2 B1 Bo The flag specified with B3B2B1B0 is reset. ZF 1 | Fn +-0 Ľ manipulation F ag A jump to the address specified with the PC₁₁ (or PC_{11}) and immediate date $P_{10}P_{9}P_{8}P_{7}P_{8}P_{5}P_{4}P_{3}P_{2}P_{1}P_{0}$ occurs. If the BANK and JMP ingructions are 0 1 1 0 1 PioPo Pe 2 2 PC ← PCii (又はPCii) JMP addr Jump in the current P10P9 P9 P2 P6 P P4 P3 P2 P1 P0 bank P7P6P5P4 P3P2P1P0 executed consecutively, PC11 A jump to the address specified with the contents of the PC whose low-order 8 bits are replaced by the E and AC contents occurs. Jump in the current JP€A 1111 1010 PC7 ~ 0 ←(E,AC) page modified by E and AC Call subroutine in the CZP addr 1 0 1 1 P3P2P1P0 STACK ⊷ (PC)+1 A subroutine in page 0 of bank 0 is called zero pagé PC11~6,PC1~0 ←0 PC5-2+P3P2P1P0 1 O I O I PicPa Pa P7 P6 P5 P4 P3 P2 P1 Po CAL addr Call subroutine in the STACK -(PC) +2 A subroutine in bank 0 is called. zero bank PCIT~0 ← OPioPaPaP P6P5P4P3P2P1P0 Ĕ RT Return from subroutine 0 1 1 0 0 0 1 0 1 PC - (STACK) A return from a subroutine occurs, Return from interrupt RTI 00100010 PC +(STACK) A return from an interrupt service routine ZF CF occurs routine CF ZF ← CSF.ZSF Effective only when used immediately bef the JMP instruction. PC11+ (PC11) BANK Change bank 1 1 1 1 1 1 0 1 The bank is changed. If a single bit of the AC specified with the immediate data $t_1 t_0$ is 1, a branch to the address specified with the immediate data $P_2 P_6 P_6 P_4 P_3 P_2 P_1 P_0$ within the same page occurs. 0 1 1 1 0 0 tito 2 2 P7P6P5P4 P3P2P1P0 PC1 ~ 0 - P7 P6P5P4 P3 P2P1P0 Mriemanic is 8A0 to 8A3 according to the value of L BAt addr Branch on AC bit 1 ACt = 1 If a single bit of the AC specified with the immediate data $t_1 t_0$ is 0, a branch to the address specified with the immediate Mnemonic is BNA0 to BNA3 according to the value of c. BNAtaddr Branch on no AC bit 0 0 1 1 0 0 tito 2 2 PC7 ~0 ← P7 P6P5P4 P7 P6 P5 P4 P3 P2 P1 P0 P 3 P 2 P 1 P 0 If ACt = 0data P7P6P5P4P3P2P1P0 within the same page occurs, If a single bit of the M(DP) specified with the immediate data t_1t_0 is 1, a branch to the address specified with the Immediate data $P_76P_6P_4P_3P_2P_1P_0$ within the same 0 1 1 1 0 1 t 1 t 0 2 2 P / P6P5P4 P3P2P1P0 Mnemonic is BMO to GMD according to the value of t. BMI add/ Branch on M bit PC 7 ~0 - P7 P8 P5 P4 P3 P2 P1 P0 $(M(DP, t_1 t_0)) = 1$ 0 0 1 1 0 1 t 1 t 0 2 P 7 P 6 P 5 P 4 P 3 P 2 P 1 P 0 Mnemanic & BNMO to BNM3 according to the value of L. PC7~0 - P7P6P5P4 BNMt addr Branch on no M bit P3 P2 P1 P0 if (M(DP.t 110))=0 Dege occurs. page occurs. If a single bit of port $P(DP_L)$ specified with the immediate data t_1t_0 is 1, a branch to the address specified with the immediate data $P_7P_6P_4P_3P_2P_1P_0$ within the same provided of the sam **Janet** 0 1 1 1 1 0 t 1 0 P) P6 P5 P4 P3 P2 P1 P0 PC1~0 + P1P6P5P4 Mnemonic is BPO to BPO according to the value of t. BP1 addr Branch on Port bit 2 2 P3 P2 P1 P0 (1 (P(DPL tito))=1 within the same of

LC6520C,6520H,6522C,6522H

		P7 P6 P5 P4 P3 P	P2 P1 P0	$P_3P_2P_1P_0$ if (P(DPL, t it of) = 0	with the immediate data $t_1 t_0$ is D, a branch to the address specified with the immediate data $P_7 P_8 P_5 P_4 P_3 P_2 P_1 P_0$ within the same near occurs.	BNP3 according the value of t.
BTM addr	Branch on timer	0 1 1 1 1 1 P 7 P 6 P 5 P 4 P 3 P	1 0 0 2 2 2 P1 P0	$PC7 \sim_0 \leftarrow P7 P_6 P_5 P_4$ $P_3 P_2 P_1 P_0$ if TMF = 1 then TMF $\leftarrow 0$	If the TMF is 1, a brench to the address specified with the immediate data $P_7P_6P_5P_4P_3P_2P_1P_0$ within the same page occurs. The TMF is reset.	TMF

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Status flag Bytes Cycles Function Description* Mnemonic affected D7 D6 D5 D4 D3 O2 D1 D0 - P>P6P5 Pa If the TMF is 0, a branch to the address specified with the immediate data P3P3P2 P0 with the same = 0 page occurs. The TMF is reset. 0 0 1 1 1 1 0 0 2 2 PC7~0 - P7P6P5P4 TMP BNTM addr Branch on no timer P7 P6 P5 P4 P3 P2 P1 P0 I TMF=0 then TMF -0 If the EXTF is 1, a branch to the address specified with the immediate data $P_7P_6P_5P_4P_3P_2P_1P_0$ within the same page occurs. The EXTF is reset. PC7~0 - P7 P6 P5 P4 0 1 1 1 1 1 0 1 2 2 EXTE Branch on interrupt P7 P6 P5 P4 P3 P2 P1 P0 P3 P2 P1 P0 I EXTE = 1

LC6520C,6520H,6522C,6522H

Instruction code

Inthruct group

Bi addr

1			1		1 1				
Branch instructions	BNI addi	Branch on no interrupt	0 0 1 1 P7P6P5P4	1 1 0 1 P3 P2 P1 P0	2	PC 7 \sim 0 \leftarrow P7 P6 P5 P4 P3 P2 P1 P0 IL EXTF = 0 then EXTF \leftarrow 0	If the EXTF is 0, a branch to the address specified with the immediate data $P_7^{P_6}P_5^{P_4}P_3^{P_2}P_1^{P_0}$ within the same page occurs. The EXTF is reset.	EXTE	
	BC addr	Branch on CF	0 1 1 1 P7P6P5P4	1 1 1 1 P3P2P1P0	2	$\frac{PC_{7} \sim 0 \leftrightarrow P_{7}P_{6}P_{5}P_{4}}{P_{3}P_{2}P_{1}P_{0}}$ if CF = 1	If the CF is 1, a branch to the address specified with the immediate data $P_7 P_6 P_5 P_4 P_3 P_2 P_1 P_0$ within the same page occurs.		
	BNC addr	Branch on no CF	0 0 1 1 P7P6P5P4	1 1 1 1 P3 P2 P+ Po	2	PC 7 → 0 ← P7 P6 P5 P4 P3 P2 P1 P0 if CF = 0	If the CF is 0, a branch to the address specified with the immediate data $P_7P_6P_6P_4P_3P_2P_1P_0$ within the same page occurs.		
	82 addr	Branch on ZF	0 1 1 1 P7P6P5P4	1 1 J O P3P2P1P0	22	PC7 ~0 ~ P7P6P5P4 P3P2P1P0 r1 ZF = 1	If the $2F$ is 1, a branch to the address specified with the immediate data $P_7P_6P_5P_4P_3P_2P_1P_0$ within the same page occurs.		
	BNZ addr	Branch on no ZF	0 0 1 1 P7P5P5P4	1 1 1 0 P3P2P1P0	2	$\begin{array}{c} PC_{2} \sim 0 \leftarrow P_{2}P_{6}P_{5}P_{4} \\ P_{3}P_{2}P_{1}P_{0} \\ \text{if } ZF = 0 \end{array}$	If the ZF is 0, a branch to the address specified with the immediate data $P7P_6P_5P_4P_3P_2P_1P_0$ within the same page occurs.		
	BFn addi	Branch on Hag bit	1 1 0 1 P7P6P5P4	n 3 n 2 n 3 n 0 P 3 P 2 P 3 P 0	2	2 PC 2 ~ 0 ← P2 P6 P5 P4 P3 P2 P1 P0 21 Fn = 1	If the flag bit of the 16 flags specified with the immediate data $n_3 n_2 n_1 n_0$ is 1, a branch to the address specified with the immediate data $P_7 P_6 P_5 P_4 P_3 P_2 P_1 P_0$ within the same page occurs.		Mremonic is BFO to BF15 according to the value of n.
	BNFn addi	Branch on no flag bit	1 0 0 1 P7P5P5P4	поперто РзР2Р3Р6	2	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	If the flag bit of the 16 flags specified with the immediate data $n_3n_1n_0$ is 0, a branch to the address specified with the immediate data $P_7R_8P_8P_4P_8P_8P_1P_0$ within the same page occurs.		Mnemonic is BNFO to StVF I 5 according to the value of n.
ŕ	1 P	Input port to AC	0000	1 1 0 0	1	AC - (P(DPL)	Port P(DPL) contents are loaded in the AC.	ZF	
Cţio	OP	Output AC to port	0110	0001	1	1 P(DPL) + (AC)	The AC contents are outputted to port P(D	P_1.	
tput instruc	SPB bit	Set poil bit	0000	0 1 Bi Bo	1	2 P(DPL B1B0) -1	A single bit in port $P(DP_L)$ specified with the immediate data $B_1 \theta_D$ is set.		When this interaction is executed, the E contents are distrayed.
Other instructions	RPB bit	Reset port bit	0010	0 1 B1 B0	1	2 P(DPL, B(B) ←0	A single bit in port P(DPL) specified with the immediate data 8 180 is reset.	ZF	When this instruction is executed, the E contents are destroyed
	SCTL bit	Set control register bit(S)	0010 1000	1 1 0 0 B3 B2 B1 B0	2	2 CTL (CTL) V B3B2B1B0	The bits of the control register specified with the immediate data $B_3B_2B_1B_0$ are set.		
	RCTL bu	Reset control register bil(S)	0010	1 1 0 0 B3 B2 B1 B0	. 2	2 CTL ←(CTL) ∧ B3 B2 B1 B0	The bits of the control register specified with the immediate data $B_3B_2B_1B_0$ are reset.	ZF	
	WITM	Write timer	1 1 1 1	1001	1) TM++(E).(AC) TMF ++0	The E and AC contents are loaded in the timer. The TMF is reset.	TMF	
	HALT	Halt	1 1 1 1	0110	1	1 Hali	All operations stop.		Only when all pine of port PA are set at L, stop.
	NOP	No operation	0000	0000	1	1 No_operation	No operation is performed, but 1 machine cycle is consumed.		
		<u></u>		If the CL	A in	truction is used cons	ecutively in such a manner as CL	A. CLA.	

If the CLA instruction is used consecutively in such a manner as CLA, CLA, ----,

the first CLA instruction only is effective and the following CLA instructions are changed to the NOP instructions. This is also true of the LI instruction.

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Remarks